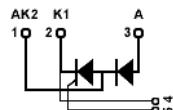


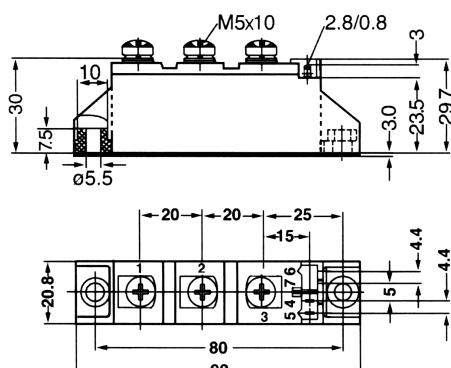
STD/SDT100

Thyristor-Diode Modules, Diode-Thyristor Modules



Type	V _{RSM} V _{DSM} V	V _{RRM} V _{DRM} V
STD/SDT100GK08	900	800
STD/SDT100GK12	1300	1200
STD/SDT100GK14	1500	1400
STD/SDT100GK16	1700	1600
STD/SDT100GK18	1900	1800
STD/SDT100GK20	2100	2000
STD/SDT100GK22	2300	2200

Dimensions in mm (1mm=0.0394")



Symbol	Test Conditions	Maximum Ratings	Unit
I _{TRMS} , I _{FRMS} I _{TAVM} , I _{FAVM}	T _{VJ} =T _{VJM} T _C =85°C; 180° sine	180 100	A
I _{TSM} , I _{FSM}	T _{VJ} =45°C V _R =0 t=10ms (50Hz), sine t=8.3ms (60Hz), sine	1700 1800	A
	T _{VJ} =T _{VJM} V _R =0 t=10ms(50Hz), sine t=8.3ms(60Hz), sine	1540 1640	
$\int i^2 dt$	T _{VJ} =45°C V _R =0 t=10ms (50Hz), sine t=8.3ms (60Hz), sine	14450 13500	A ² s
	T _{VJ} =T _{VJM} V _R =0 t=10ms(50Hz), sine t=8.3ms(60Hz), sine	11850 11300	
(di/dt) _{cr}	T _{VJ} =T _{VJM} f=50Hz, t _p =200us V _D =2/3V _{DRM} I _G =0.45A dI _G /dt=0.45A/us	150 500	A/us
(dv/dt) _{cr}	T _{VJ} =T _{VJM} ; V _{DR} =2/3V _{DRM} R _{GK} =∞; method 1 (linear voltage rise)	1000	V/us
P _{GM}	T _{VJ} =T _{VJM} t _p =30us I _T =I _{TAVM} t _p =300us	10 5	W
P _{GAV}		0.5	W
V _{RGM}		10	V
T _{VJ} T _{VJM} T _{stg}		-40...+125 125 -40...+125	°C
V _{ISOL}	50/60Hz, RMS I _{ISOL} ≤1mA	3000 3600	V~
M _d	Mounting torque (M5) Terminal connection torque (M5)	2.5-4.0/22-35 2.5-4.0/22-35	Nm/lb.in.
Weight	Typical including screws	90	g

STD/SDT100

Thyristor-Diode Modules, Diode-Thyristor Modules

Symbol	Test Conditions	Characteristic Values	Unit
I_{RRM}, I_{DRM}	$T_{VJ}=T_{VJM}; V_R=V_{RRM}; V_D=V_{DRM}$	15	mA
V_T, V_F	$I_T, I_F=300A; T_{VJ}=25^\circ C$	1.74	V
V_{TO}	For power-loss calculations only ($T_{VJ}=T_{VJM}$)	0.85	V
r_T		3.2	$m\Omega$
V_{GT}	$V_D=6V; T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	1.5 1.6	V
I_{GT}	$V_D=6V; T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	100 200	mA
V_{GD}	$T_{VJ}=T_{VJM}; V_D=2/3V_{DRM}$	0.25	V
I_{GD}	$T_{VJ}=T_{VJM}; V_D=2/3V_{DRM}$	10	mA
I_L	$T_{VJ}=25^\circ C; t_p=30\mu s; V_D=6V$ $I_G=0.45A; dI/dt=0.45A/\mu s$	200	mA
I_H	$T_{VJ}=25^\circ C; V_D=6V; R_{GK}=\infty$	150	mA
t_{gd}	$T_{VJ}=25^\circ C; V_D=1/2V_{DRM}$ $I_G=0.45A; dI/dt=0.45A/\mu s$	2	us
t_q	$T_{VJ}=T_{VJM}; I_T=150A; t_p=200\mu s; -di/dt=10A/\mu s$ $V_R=100V; dv/dt=20V/\mu s; V_D=2/3V_{DRM}$	typ. 185	us
Q_s	$T_{VJ}=T_{VJM}; I_T, I_F=50A; -di/dt=6A/\mu s$	170	uC
I_{RM}		45	A
R_{thJC}	per thyristor/diode; DC current per module	0.22 0.11	K/W
R_{thJK}	per thyristor/diode; DC current per module	0.42 0.21	K/W
ds	Creeping distance on surface	12.7	mm
da	Creepage distance in air	9.6	mm
a	Maximum allowable acceleration	50	m/s^2

FEATURES

- * International standard package
- * Copper base plate
- * Planar passivated chips
- * Isolation voltage 3600 V~

APPLICATIONS

- * DC motor control
- * Softstart AC motor controller
- * Light, heat and temperature control

ADVANTAGES

- * Space and weight savings
- * Simple mounting with two screws
- * Improved temperature and power cycling
- * Reduced protection circuits



STD/SDT100

Thyristor-Diode Modules, Diode-Thyristor Modules

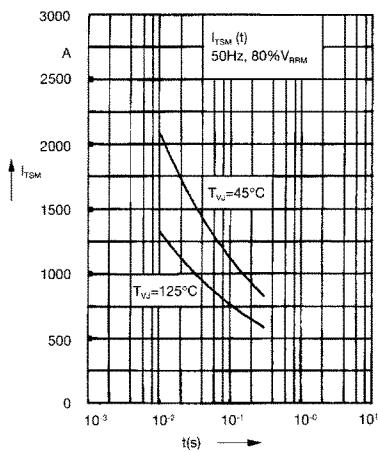


Fig. 1 Surge overload current
 I_{TSM}, I_{FSM} : Crest value, t : duration

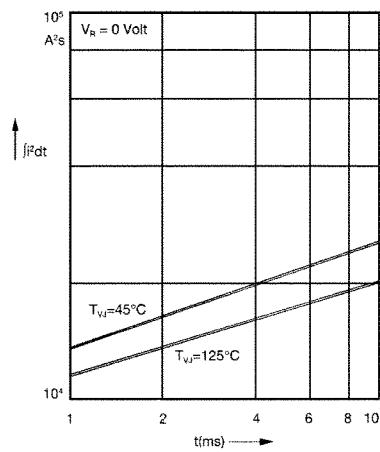


Fig. 2 $\int i^2 dt$ versus time (1-10 ms)

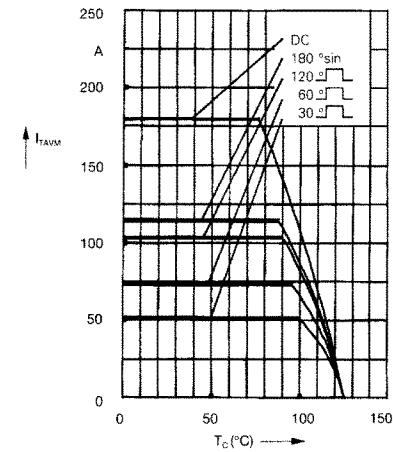


Fig. 2a Maximum forward current
at case temperature

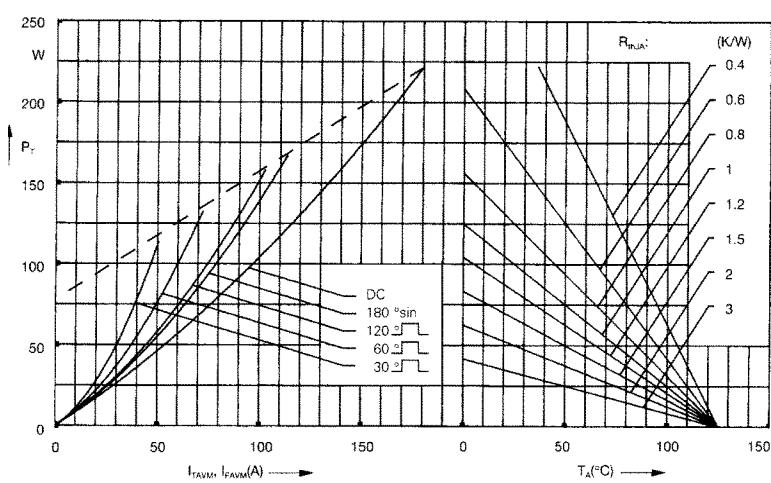


Fig. 3 Power dissipation versus on-state current and ambient temperature
(per thyristor or diode)

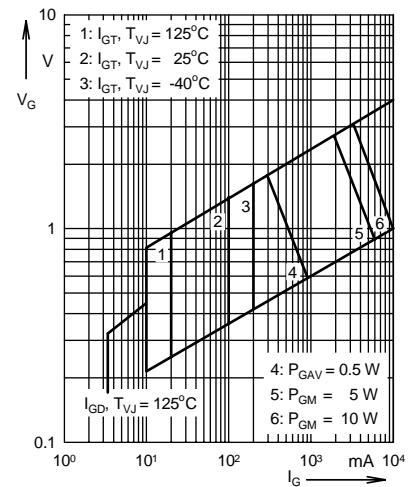


Fig. 4 Gate trigger characteristics

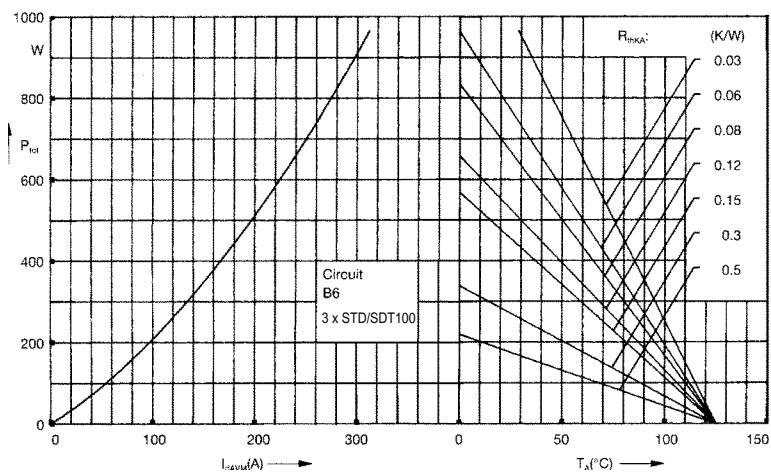


Fig. 5 Three phase rectifier bridge: Power dissipation versus direct output current
and ambient temperature

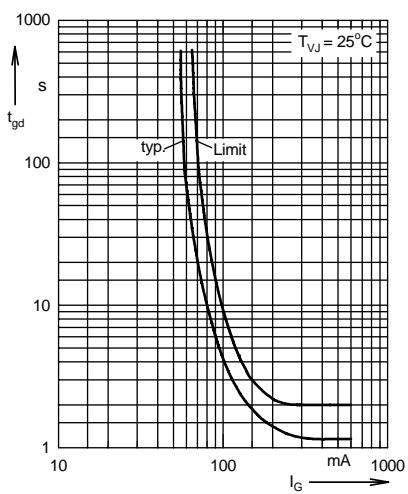


Fig. 6 Gate trigger delay time

3 x STD/SDT100

STD/SDT100

Thyristor-Diode Modules, Diode-Thyristor Modules

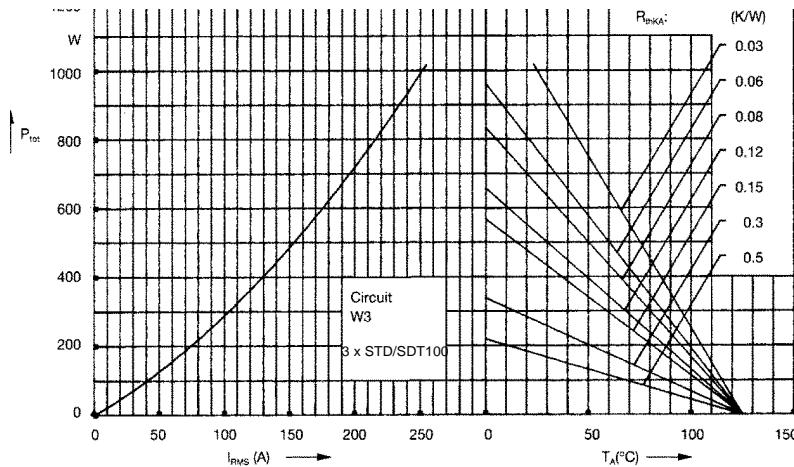


Fig. 7 Three phase AC-controller:
Power dissipation versus RMS
output current and ambient
temperature

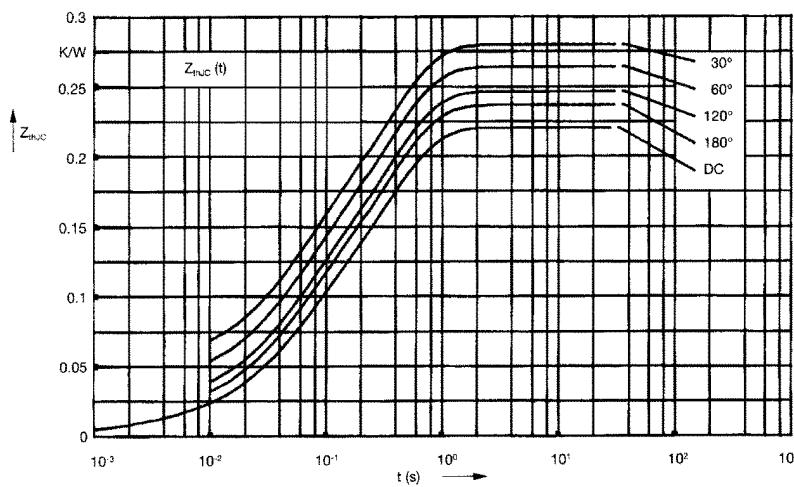


Fig. 8 Transient thermal impedance
junction to case (per thyristor or
diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.22
180°	0.23
120°	0.25
60°	0.27
30°	0.28

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0066	0.0019
2	0.0678	0.0477
3	0.1456	0.344

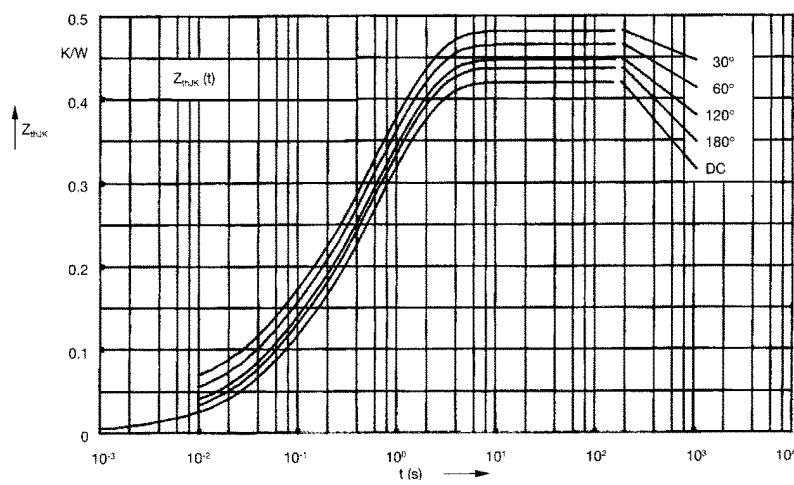


Fig. 9 Transient thermal impedance
junction to heatsink (per thyristor or
diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.42
180°	0.43
120°	0.45
60°	0.47
30°	0.48

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0066	0.0019
2	0.0678	0.0477
3	0.1456	0.344
4	0.2	1.32